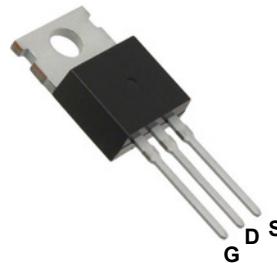
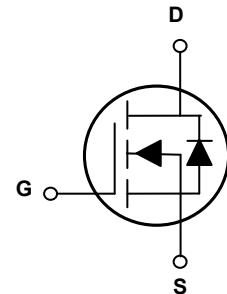


## Main Product Characteristics

$BV_{DSS}$	100V
$R_{DS(ON)}$	3.7mΩ
$I_D$	150A



TO-220



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFH0980 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	+20/-12	V
Drain Current-Continuous( $T_C=25^\circ\text{C}$ )	$I_D$	150	A
Drain Current-Continuous( $T_C=100^\circ\text{C}$ )		95	A
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	600	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	378	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	87	A
Power Dissipation( $T_C=25^\circ\text{C}$ )	$P_D$	275	W
Power Dissipation-Derate Above 25°C		2.22	W/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.45	°C/W
Storage Temperature Range	$T_{STG}$	-50 To +150	°C
Operating Junction Temperature Range	$T_J$	-50 To +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	-	-	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{DS}}=80\text{V}, V_{\text{GS}}=0\text{V}, T_J=85^\circ\text{C}$	-	-	10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	100	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	3.1	3.7	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=15\text{A}$	-	4.5	6	
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=3\text{A}$	-	20	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{\text{DS}}=80\text{V}, I_{\text{D}}=10\text{A}, V_{\text{GS}}=10\text{V}$	-	110	165	$\text{nC}$
Gate-Source Charge <sup>3,4</sup>	$Q_{\text{gs}}$		-	11.5	18	
Gate-Drain Charge <sup>3,4</sup>	$Q_{\text{gd}}$		-	28	42	
Turn-On Delay Time <sup>3,4</sup>	$t_{\text{d(on)}}$	$V_{\text{DD}}=50\text{V}, R_{\text{G}}=6\Omega, V_{\text{GS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	23	46	$\text{nS}$
Rise Time <sup>3,4</sup>	$t_r$		-	32	64	
Turn-Off Delay Time <sup>3,4</sup>	$t_{\text{d(off)}}$		-	157	320	
Fall Time <sup>3,4</sup>	$t_f$		-	115	230	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	6680	13300	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	1690	3380	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	78	156	
Gate Resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	1.9	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_s$	$V_G=V_D=0\text{V}, \text{Force Current}$	-	-	150	A
Pulsed Source Current	$I_{\text{SM}}$		-	-	300	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_s=1\text{A}, T_J=25^\circ\text{C}$	-	-	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}, V_{\text{GS}}=10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=87\text{A}, R_{\text{G}}=25\Omega$  Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

## Typical Electrical and Thermal Characteristic Curves

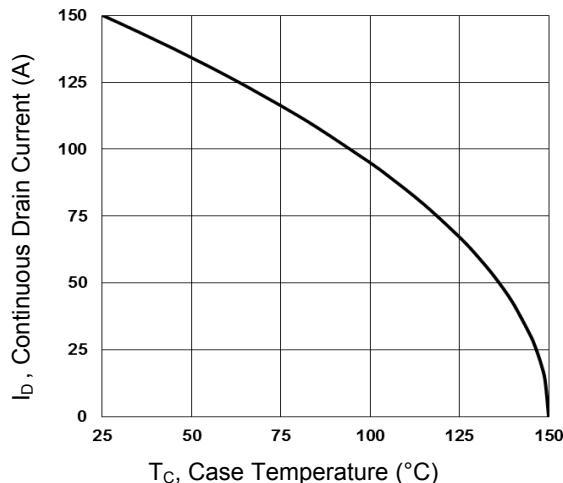


Figure 1. Continuous Drain Current vs. T<sub>c</sub>

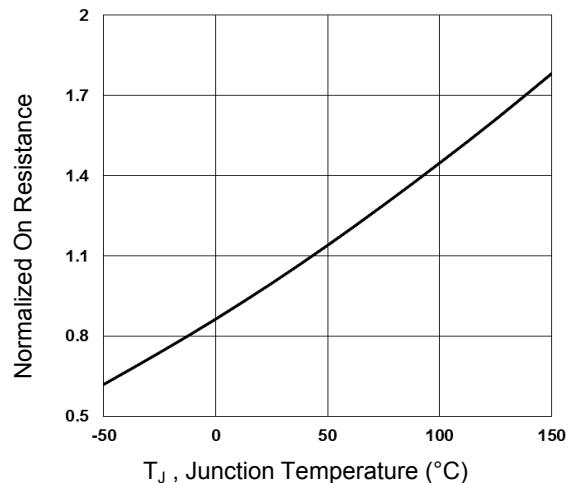


Figure 2. Normalized R<sub>DSON</sub> vs. T<sub>j</sub>

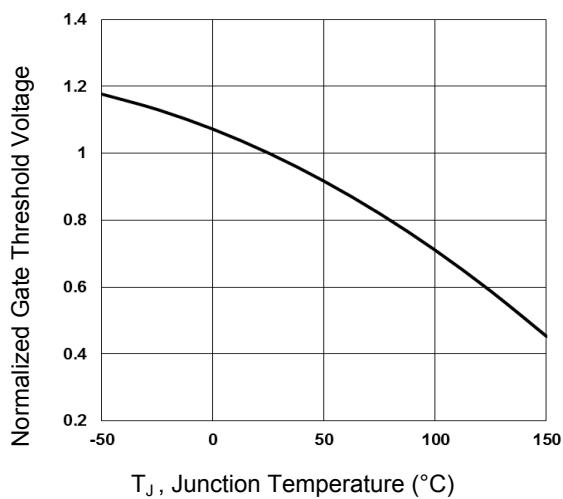


Figure 3. Normalized V<sub>th</sub> vs. T<sub>j</sub>

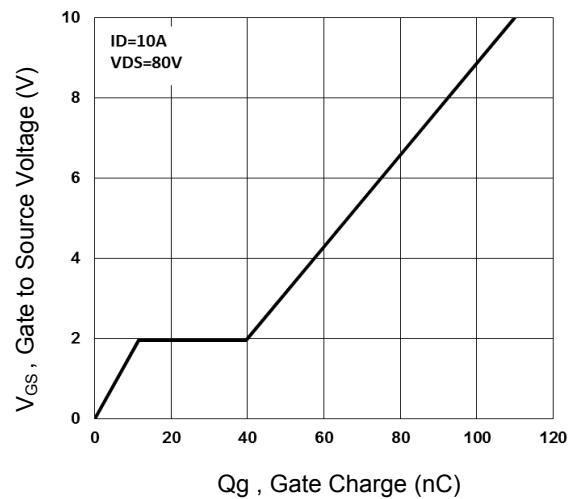


Figure 4. Gate Charge Characteristics

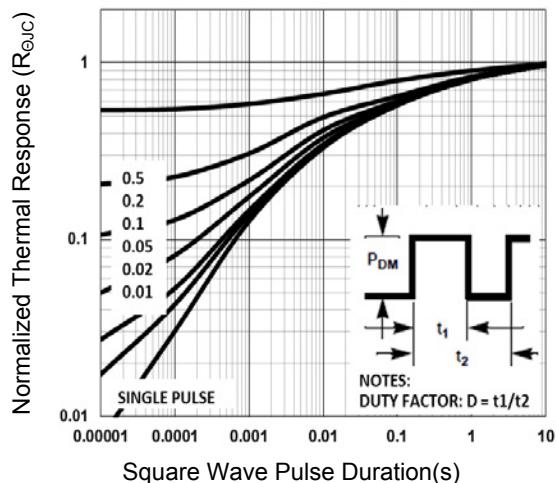


Figure 5. Normalized Transient Impedance

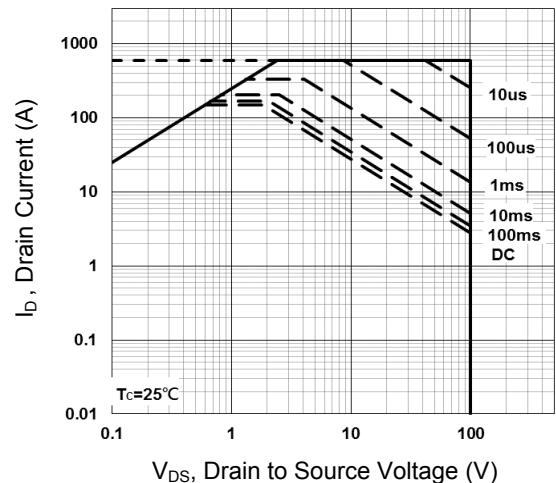


Figure 6. Maximum Safe Operation Area

### Typical Electrical and Thermal Characteristic Curves

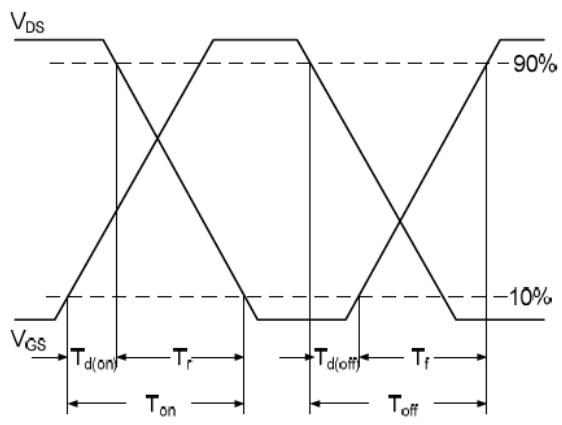


Figure 7. Switching Time Waveform

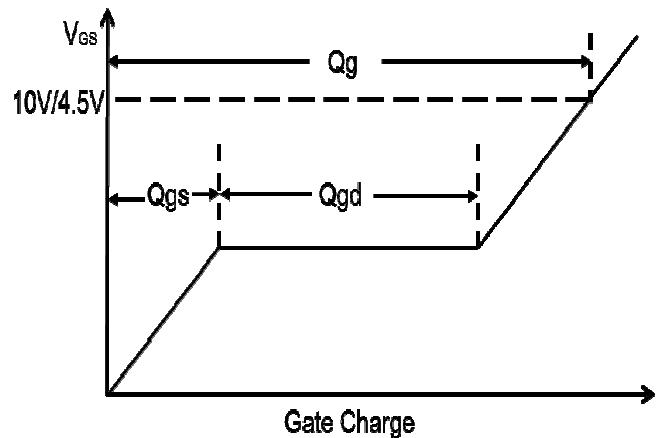
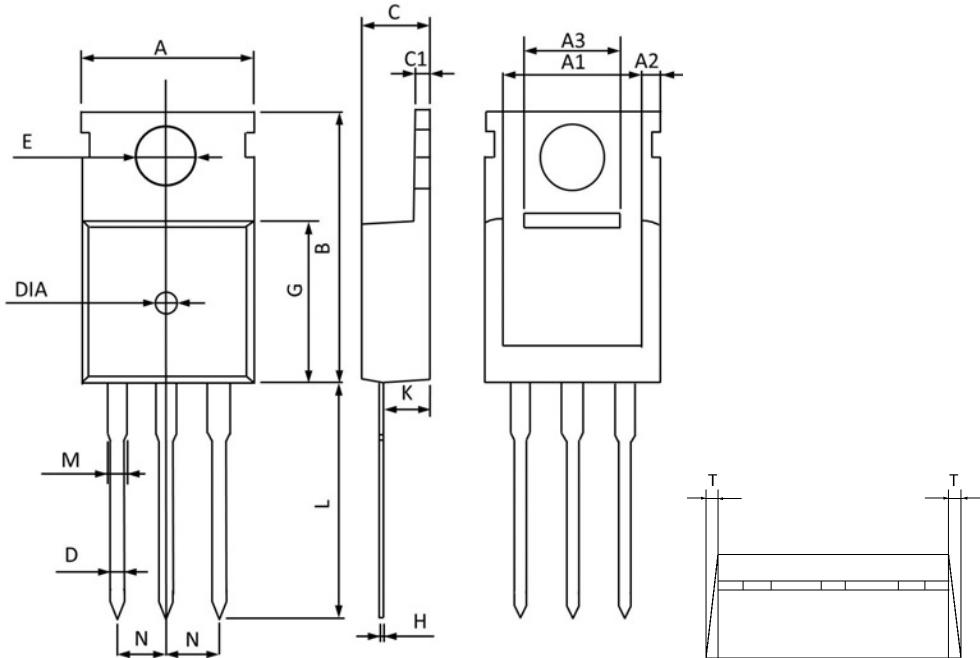


Figure 8. Gate Charge Waveform

### Package Outline Dimensions (TO-220)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.300	9.700	0.406	0.382
A1	8.840	8.440	0.348	0.332
A2	1.250	1.050	0.049	0.041
A3	5.300	5.100	0.209	0.201
B	16.200	15.400	0.638	0.606
C	4.680	4.280	0.184	0.169
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	3.800	3.400	0.150	0.134
G	9.300	8.700	0.366	0.343
H	0.600	0.400	0.024	0.016
K	2.700	2.100	0.106	0.083
L	13.600	12.800	0.535	0.504
M	1.500	1.100	0.059	0.043
N	2.590	2.490	0.102	0.098
T	W0.35		W0.014	
DIA	Φ1.5 TYP.	deep0.2 TYP.	Φ0.059 TYP.	deep0.008 TYP.